PCN Number:	20140410001			**PCN Date:**	04/29/2014
Title:	Assembly/test site move from Amkor K1 to TI Taiwan for Select Devices				
Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services
Proposed 1st Ship Date:	07/29/2014	**Estimated Sample Availability:**	Date provided at sample request		

Change Type:					
☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Assembly/test site move from Amkor K1 to TI Taiwan for Select Devices. Material differences are as follows:

	Amkor K1	TI Taiwan
Mount Compound	101361223	4208458
Mold Compound	101319571	4211649
Lead Finish	Matte Sn	NiPdAu

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Closure of the Amkor K1 assembly and test facility. Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Sample Product Shipping Label (not actual product label)

Assembly Site

Amkor K1	Assembly Site Origin (22L)	ASO: AMN
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI

ASSEMBLY SITE CODES: AMN =7, TAI =T

Product Affected:		
ADS5411IPGP	ADS5423IPGP	ADS5424IPGP
ADS5411IPGPR	ADS5423IPGPR	ADS5424IPGPR

Qualification Data:

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : ADS5423IPGP (MSL 3-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4211649
# Pins-Designator, Family:	52-PGP, HTQFP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mils Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size / Fail		
		Lot#1	Lot#2	Lot#3
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Moisture Sensitivity	(level 3 @ 260C +5/-0C)	12/0	12/0	12/0

Reference Qualification Data:

Qualification Data: 04/17/2014

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: 6964BDC0PAPG4 (MSL 3-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4211649
# Pins-Designator, Family:	64-PAP, HTQFP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mils Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**Autoclave 121C	121C (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150C (500 cycles)	77/0	77/0	77/0
Manufacturability (Assembly)		Pass	-	-
Moisture Sensitivity	Level 3-260C	12/0	12/0	12/0

**- Preconditioning sequence: Level 3-260C.

Qual Vehicle 2: D610A3BPYP225 (MSL 4-260C)

Package Construction Details

Assembly Site:	TI Taiwan	Mold Compound:	4211649
# Pins-Designator, Family:	208-PYP, HTQFP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mils Dia., Au

Qualification: ☐ **Plan** ☒ **Test Results**				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp Storage	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150C (500 cycles)	77/0	77/0	77/0
Manufacturability (Assembly)		Pass	-	-
Moisture Sensitivity	Level 4-260C	20/0	20/0	20/0
**- Preconditioning sequence: Level 4-260C.				

Qual Vehicle 3: DRV593VFP (MSL 2-260C)			
Package Construction Details			
Assembly Site:	TI Taiwan	Mold Compound:	4211649
# Pins-Designator, Family:	32-VFP, HLQFP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mils Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**			
Reliability Test	Conditions	Sample Size (PASS/FAIL)	
		Lot#1	Lot#2
**High Temp Storage	170C (420 Hrs)	77/0	77/0
**Autoclave 121C	121C (96 Hrs)	77/0	77/0
**Temperature Cycle	-65/150C (500 cycles)	77/0	77/0
Manufacturability (Assembly)		Pass	-
**- Preconditioning sequence: Level 2-260C.			

Qual Vehicle 4: SLK2511CPZP (MSL 3-260C)			
Package Construction Details			
Assembly Site:	TI Taiwan	Mold Compound:	4211649
# Pins-Designator, Family:	100-PZP, HTQFP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mils Dia., Cu

Qualification: ☐ **Plan** ☒ **Test Results**				
Reliability Test	Conditions	Sample Size (PASS/FAIL)		
		Lot#1	Lot#2	Lot#3
**High Temp Storage	170C (420 Hrs)	77/0	77/0	77/0
**Autoclave 121C	121C (96 Hrs)	77/0	77/0	77/0
**Temperature Cycle	-65/150C (500 cycles)	77/0	77/0	77/0
Manufacturability (Assembly)		Pass	-	-
Moisture Sensitivity	Level 3-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com